

IN THE CLAIMS

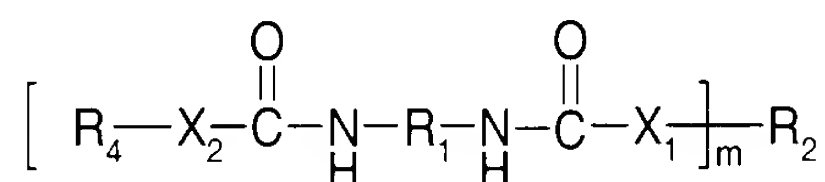
Please amend the Claims as follows. Please cancel Claims 1, 3-5, 7, 9, 19, and 20. Please add new Claims 21-32. A marked-up version of the amended claims showing changes made is attached.

21. (new) A circuit board comprising of:

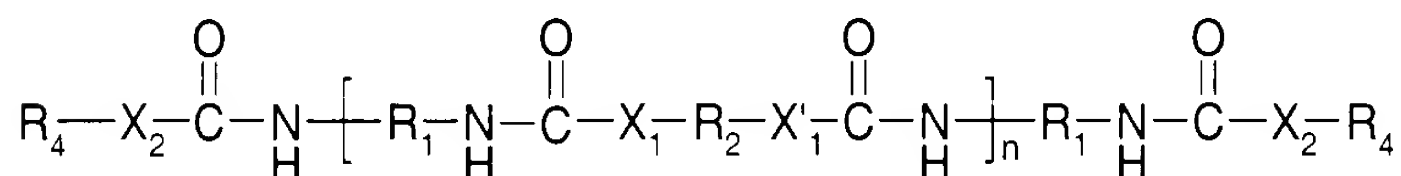
a chip attached to said circuit board by an electrically conductive adhesive,

wherein said electrically conductive adhesive comprises of, an epoxide-modified polyurethane resin, a cross-linking agent, an adhesion promoter, and a conductive filler,

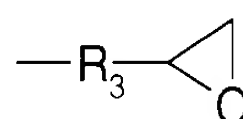
wherein said epoxide-modified polyurethane resin has the following structure:



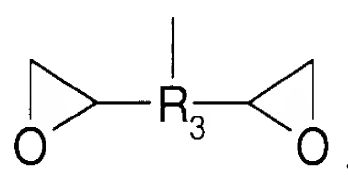
or



where m is 2 or 3; n is one or greater; R₁ is an aliphatic hydrocarbon radical, a cycloaliphatic hydrocarbon radical, an aromatic hydrocarbon radical, or an araliphatic hydrocarbon radical; R₂ is an aliphatic hydrocarbon radical, a cycloaliphatic hydrocarbon radical, an alkoxy radical, a polyester; or a polyether; R₄ is either:



or



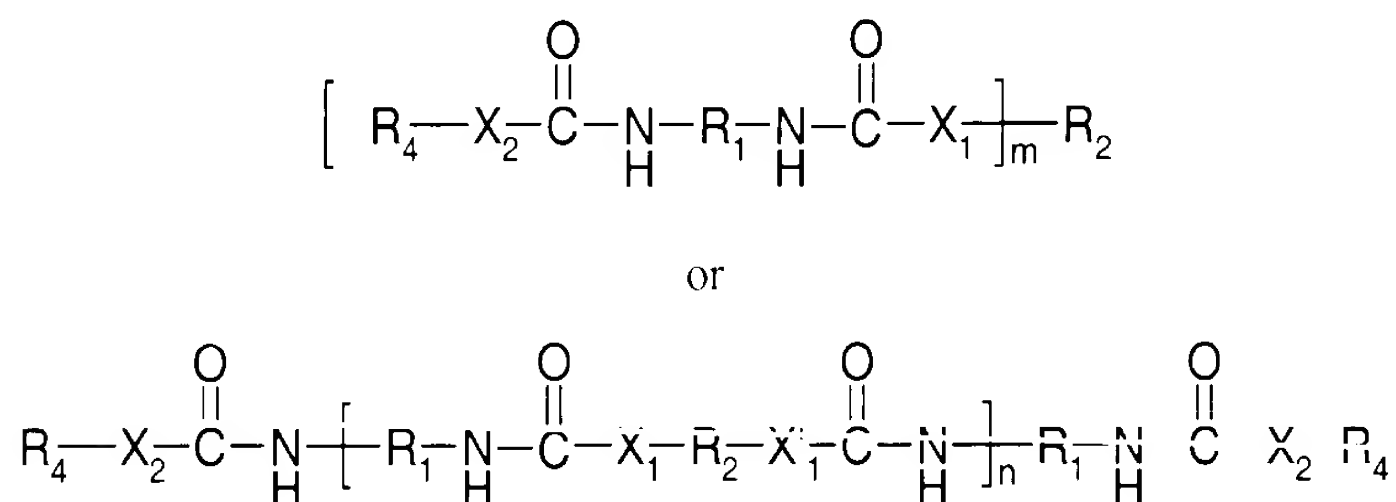
R₃ is an aliphatic hydrocarbon radical, a cycloaliphatic hydrocarbon radical, an alkoxy radical, a polyester, or a polyether; and X₁ and X₂ are either a single bond, -O-, -COO-, -NH-, or -S-.

22. (new) The circuit board as defined in Claim 21, wherein the cross-linking agent is selected from the group consisting of aliphatic amines, aromatic amines, carboxylic acid anhydrides, thiols, alcohols, phenols, isocyanates, tertiary amines, boron complexes, inorganic acids, hydrazides, imidazoles and their derivatives, and modified products thereof.
23. (new) The circuit board as defined in Claim 22 wherein the cross-linking agent is a carboxylic acid anhydride cross-linker
24. (new) The circuit board as defined in Claim 21, wherein the cross-linking agent is selected from the group consisting of liquid imidazoles and anhydrides.
25. (new) The circuit board as defined in Claim 21, wherein the adhesion promoter is selected from the group consisting of alkylchlorosilanes, dialkyldichlorosilanes, alkyltrichlorosilanes; organosilane esters; vinylsilanes; aminoalkylsilanes; diaminoalkylsilanes; styrylaminoalkylsilanes; ureidoalkylsilane esters; epoxyalkylsilane esters; alkoxysilanes; acryloxyalkylsilane esters; methacryloxyalkylsilane esters; and mercaptoalkylsilane esters, and combinations thereof..
26. (new) The circuit board as defined in Claim 21, wherein said conductive filler is a solid metal particle selected from the group of nickel, copper, aluminum, palladium, silver, gold, and platinum.
27. (new) The circuit board as defined in Claim 26, wherein said conductive filler is silver flakes.
28. (new) The circuit board as defined in Claim 21, wherein said conductive filler is selected from the group consisting of carbon black, carbon fiber, and graphite.
29. (new) The circuit board as defined in Claim 21, further comprising one or more

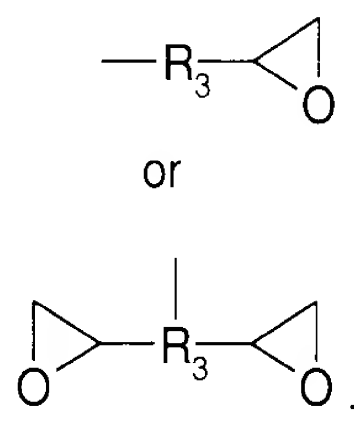
of (e) an epoxy resin; (f) a catalyst; and (g) a diluent.

30.(new) A method of joining electrically conductive materials, which comprises of applying an electrically conductive adhesive composition to at least one of said electrically conductive materials, wherein said electrically conductive adhesive composition consists of, an epoxide-modified polyurethane resin, a cross-linking agent, an adhesion promoter, and a conductive filler,

wherein said epoxide-modified polyurethane resin has the following structure:



where m is 2 or 3; n is one or greater; R₁ is an aliphatic hydrocarbon radical, a cycloaliphatic hydrocarbon radical, an aromatic hydrocarbon radical, or an araliphatic hydrocarbon radical; R₂ is an aliphatic hydrocarbon radical, a cycloaliphatic hydrocarbon radical, an alkoxy radical, a polyester; or a polyether; R₄ is either:



R₃ is an aliphatic hydrocarbon radical, a cycloaliphatic hydrocarbon radical, an alkoxy radical, a polyester, or a polyether; and X₁ and X₂ are either a single bond, -O-; -COO-; -NH-; or -S-.

31. (new) The method of claim 30 wherein said electrically conductive materials are

at least one of the following; a chip and a printed circuit board.

32. (new) The method of claim 30 wherein said electrically conductive adhesive composition further comprises of at least one of the following; an epoxy resin, a catalyst, and a diluent.